


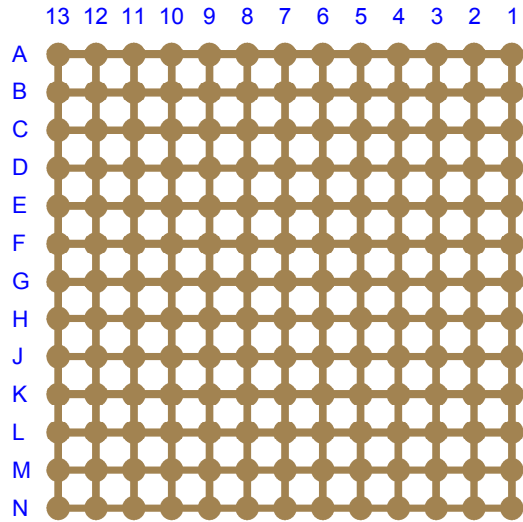
SECTION A-A

- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.635.
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.508mm (20 MIL).
 - 5) PAD Cu DIAMETER: 0.685mm (27 MIL).
 - 6) SUBSTRATE MATERIAL: FR4.
 - 7) DUMMY DIE IS OPTIONAL. PIN A1 DOT NOT MARKED.
 - 8) DAISY CHAIN PATTERN (ALL I/O CONNECTED).
 - 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

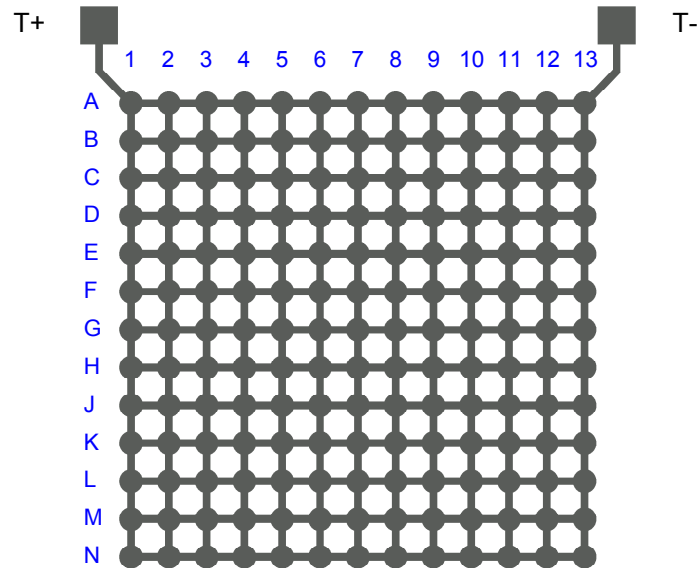
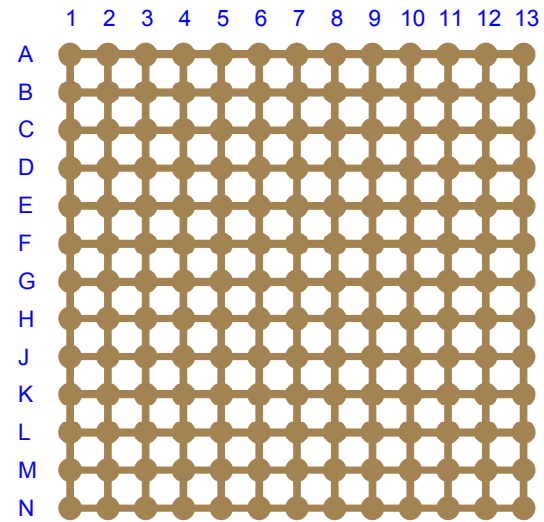
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
LBGA169T1.0C-BUS	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	NO
LBGA169T1.0C-BUS-D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
LBGA169T1.0-BUS	Sn63/Pb37	Sn63	NO	NO
LBGA169T1.0-BUS-D	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE				
DRAWN T.Au	02/04/14				
ENG M. Hart	02/04/14	TITLE LBGA169T1.0-BUS BUS CIRCUIT DUMMY			
MFG		SCALE 6.5:1	SIZE A	DRAWING NO. 511307	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 2
CUST					
REVISED					

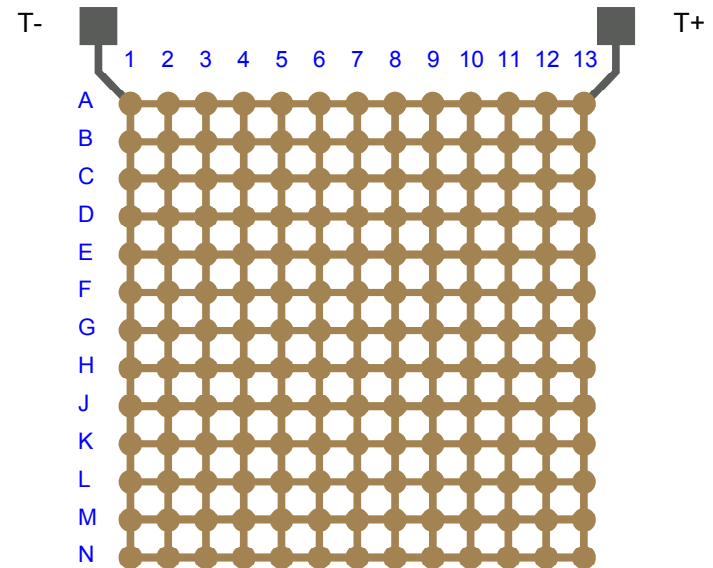
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.685mm (27 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.203mm (8 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.508mm (20 MIL).

TopLine®			
TITLE		LBGA169T1.0-BUS BUS CIRCUIT DUMMY	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	511307	A
DO NOT SCALE DRAWING			SHEET 2 OF 2